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Important Deadlines

Abstract Submission: March 6, 2009

Full Papers Submission: May 1, 2009

Notification of Acceptance: June 26, 2009

Camera Ready Copy: July 31, 2009

Author's Registration: July 31, 2009

Advance Registration: August 28, 2009

2009 IEEE Toronto International Conference Science and Technology for Humanity (TIC-STH 2009)

<http://www.TIC-STH2009.org>

September 26-27 2009, Toronto Marriott Downtown Eaton
Centre, Toronto, Canada

Education

Call for Papers

Papers are invited on a broad range of educational issues relating to science and technology with a focus on such themes as sustainability, the environment, social development and other impacts on society.

All submissions must conform to the TIC-STH 2009 submission policy and should be in English language.

Symposium Technical Program Committee

Chair: Bob Dony, University of Guelph

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